LN2162C68TR

Surface Mounting Chip LED

GW Bi-Color Type

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol Rating		Unit
Power dissipation	P _D	45	mW
Forward current	I _F	15	mA
Pulse forward current *	I _{FP}	60	mA
Reverse voltage	V _R	3	v
Operating ambient temperature	T _{opr}	-25 to +80	°C
Storage temperature	T _{stg}	-30 to +85	°C

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

• Orange

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Forward current	I _F	15	mA	
Pulse forward current *	I _{FP}	60	mA	
Reverse voltage	V _R	3	V	
Operating ambient temperature	T _{opr}	-25 to +80	°C	
Storage temperature	T _{stg}	-30 to +85	°C	

Note) *: The condition of I_{FP} is duty 10%, Pulse width 1 msec.

Electro-Optical Characteristics $T_a = 25^{\circ}C$

Pure	Green
	Pure

Parameter		Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity		Io	"THE	1.2	2.5		mcd
Forward current		Nº IF	5		10		mA
Forward voltage	1.0	V _F	$I_{\rm F} = 10 {\rm mA}$		2.05	2.8	V
Peak emission wavelength	24	$\lambda_{\rm P}$	$I_F = 10 \text{ mA}$		555		nm
Spectral half band width	aller	Δλ	$I_{\rm F} = 10 {\rm mA}$		25		nm
Reverse current	64	I _R	$V_R = 3 V$			10	μΑ

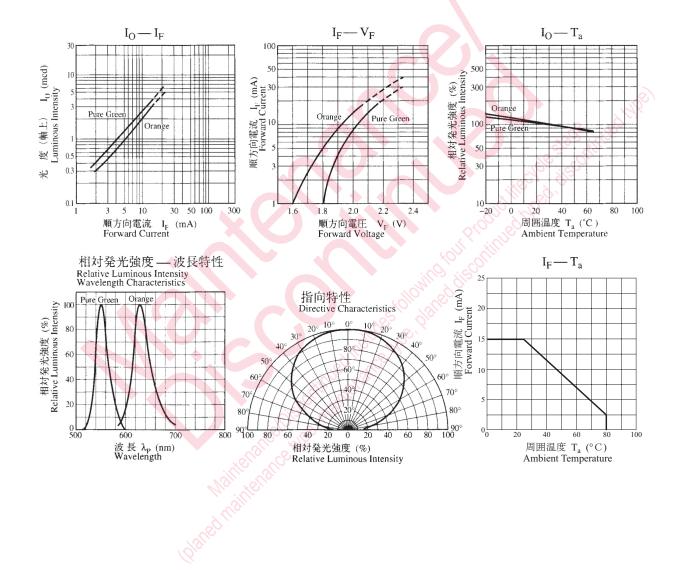
Lighting Color / Lens Color

- Pure Green / Clear
- Orange / Clear

Electro-Optical Characteristics (Continued) $T_a = 25^{\circ}C$

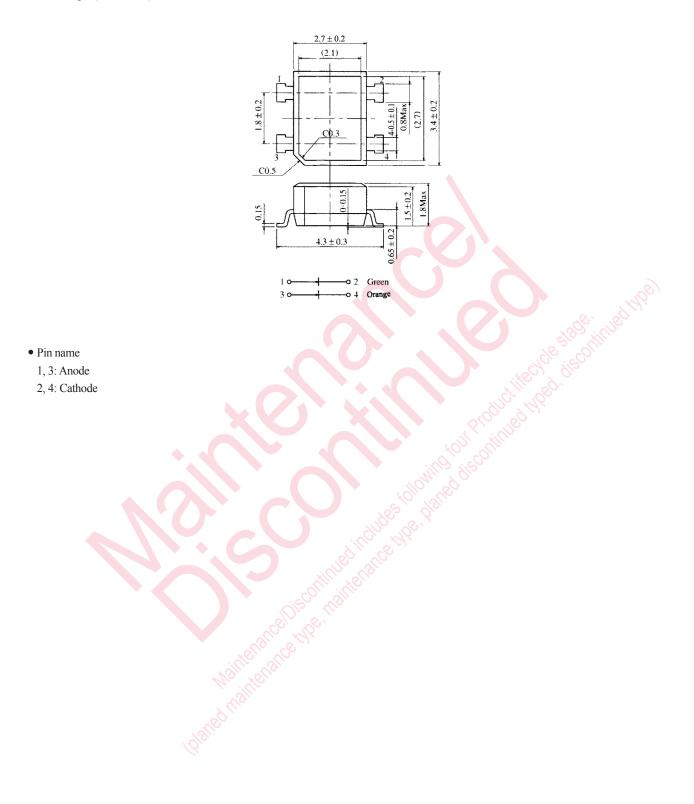
• Orange

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Luminous intensity	I _O		0.8	2.1		mcd
Forward current	$I_{\rm F}$			10		mA
Forward voltage	V _F	$I_{\rm F} = 10 \text{ mA}$		1.95	2.8	V
Peak emission wavelength	λ_{P}	$I_{\rm F} = 10 \text{ mA}$		630		nm
Spectral half band width	Δλ	$I_{\rm F} = 10 \text{ mA}$		40		nm
Reverse current	I _R	$V_R = 3 V$			10	μΑ



Panasonic

Package (Unit: mm)



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